

Abstract of the Disclosure

A system, apparatus, and method for reducing contaminants of semiconductor device fabrication equipment components, featuring a manifold having a passageway in fluid communication with to a plurality of inlets and for providing a purge fluid to removably connected components to undergo contaminant reduction. The inlets are connected to a plurality of manifold valves to which components are removably connected. The manifold valves are operable to place connected components into and out of fluid communication with the inlets and the passageway. A fluid source supplies purge fluid to the manifold and a pump is connected to the manifold to remove fluid from the system. In one embodiment an oven is connected to the system for outgassing and for reduction of moisture in additional components.